

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A bonding structure of plastic parts, comprising:

a first plastic part comprising an insert-molded in which a wiring board at least partially surrounded by plastic and at least one wiring board holding hole extending through the plastic that at least partially surrounds the wiring board, connected to a connection terminal is provided by insert molding, said first plastic part having a holding hole for holding said wiring board wherein the wiring board is connected to a connection terminal;

a second plastic part comprising a bonding face bonded to said first plastic part;

wherein excess plastic material selectively located in an area [[a]] surrounding [[of]] said at least one holding hole provided in said first plastic part and a bonding face of said second plastic part to which said first plastic part is bonded to the bonding face of the second plastic part are bonded to each other.

2. (Currently Amended) A bonding structure of plastic parts, comprising:

a first plastic part comprising an insert-molded in which a wiring board at least partially surrounded by plastic, connected to a connection terminal is provided by insert molding; wherein the wiring board is connected to a connection terminal; and

a second plastic part comprising bonded to said first plastic part, having a terminal introducing hole in which said connection terminal is introduced;

wherein excess plastic material selectively located in an area [[a]] surrounding [[of]] said connection terminal of said first plastic part and a surrounding of said terminal introducing hole of said second plastic part are bonded to each other.

3. (Currently Amended) A bonding structure of plastic parts, comprising:

a first plastic part comprising an insert-molded in which a wiring board at least partially surrounded by plastic and at least one wiring board holding hole extending through the plastic that at least partially surrounds the wiring board, connected to a connection

~~terminal is provided by insert molding, said first plastic part having a holding hole for holding said wiring board; wherein the wiring board is connected to a connection terminal; and~~

a second plastic part comprising a bonding face and ~~bonded to said first plastic part, having~~ a terminal introducing hole in which said connection terminal is introduced;

wherein excess plastic material selectively located in an area [[a]] surrounding [[of]] said at least one holding hole ~~provided in said first plastic part and a bonding face of said second plastic part to which said first plastic part is bonded to the bonding face of the second plastic part, are bonded to each other, and~~

wherein excess plastic material selectively located in an area [[a]] surrounding [[of]] said connection terminal ~~of said first plastic part and a surrounding of said terminal~~ introducing hole ~~of said second plastic part~~ are bonded to each other.

4. (Currently Amended) The bonding ~~boding~~ structure according to claim 1, wherein said bonding structure further comprises a third plastic part comprising an ~~in which another insert-molded~~ wiring board ~~is provided by insert molding~~, said third plastic part comprising at least one wiring board ~~having another~~ holding hole for holding said ~~another wiring board~~, and

wherein excess plastic material [[a]] surrounding [[of]] said at least one ~~another~~ holding hole of said third plastic part and a bonding face of said first plastic part opposed to said at least one ~~another~~ holding hole of said third plastic part are bonded to each other so that said third plastic part is stacked to said first plastic part.

5. (Currently Amended) The bonding ~~boding~~ structure according to claim 2, wherein said bonding structure further comprises a third plastic part comprising an insert-molded ~~in which another~~ wiring board ~~is provided by insert molding~~, said third plastic part comprising at least one wiring board ~~having another~~ holding hole for holding said ~~another wiring board~~, and

wherein excess plastic material [[a]] surrounding [[of]] said at least one ~~another~~ holding hole of said third plastic part and a bonding face of said first plastic part opposed to said at least one ~~another~~ holding hole of said third plastic part are bonded to each other so that said third plastic part is stacked to said first plastic part.

6. (Currently Amended) The ~~bonding~~ ~~beding~~ structure according to claim 3, wherein said bonding structure further comprises a third plastic part comprising an insert-molded in which another wiring board is provided by insert-molding, said third plastic part comprising at least one wiring board ~~having another~~ holding hole ~~for holding said another wiring board~~, and wherein excess plastic material ~~[[a]]~~ surrounding ~~[[of]]~~ said at least one another holding hole of said third plastic part and a bonding face of said first plastic part opposed to said at least one another holding hole of said third plastic part are bonded to each other so that said third plastic part is stacked to said first plastic part.

7. (Withdrawn) A method of bonding a first plastic part in which a wiring board connected to a connection terminal is provided by insert-molding to a second plastic part, the method comprising the steps of:

providing a hole side projected portion at either one of a surrounding of a holding hole for holding said wiring board provided in said first plastic part and a part of said second plastic part which is opposed to said surrounding of said holding hole;

abutting said hole side projected portion with a bonding face of another of said surrounding of said holding hole and said part of said second plastic part;

applying an ultrasonic wave to a bonding portion of said first and second plastic parts so as to melt said hole side projected portion; and

bonding said surrounding portion of said holding hole and said part of said second plastic part to each other.

8. (Withdrawn) A method of bonding a first plastic part in which a wiring board connected to a connection terminal is provided by insert-molding to a second plastic part having a terminal introducing hole in which said connection terminal is introduced, the method comprising the steps of:

providing a terminal side projected portion at either one of a surrounding of said connection terminal in said first plastic part and a surrounding of said terminal introducing hole in said second plastic part which is opposed to said surrounding of said connection terminal;

abutting said terminal side projected portion with a bonding face of another of said surrounding of said connection terminal and said surrounding of said terminal introducing hole;

applying an ultrasonic wave to a bonding portion of said first and second plastic parts so as to melt said terminal side projected portion; and

bonding said surrounding portion of said connection terminal and said surrounding of said terminal introducing hole to each other.

9. (Withdrawn) A method of bonding a first plastic part in which a wiring board connected to a connection terminal is provided by insert-molding to a second plastic part having a terminal introducing hole in which said connection terminal is introduced, the method comprising the steps of:

providing a hole side projected portion at either one of a surrounding of a holding hole for holding said wiring board provided in said first plastic part and a part of said second plastic part which is opposed to said surrounding of said holding hole, and a terminal side projected portion at either one of a surrounding of said connection terminal in said first plastic part and a surrounding of said terminal introducing hole in said second plastic part which is opposed to said surrounding of said connection terminal;

abutting said hole side projected portion with a bonding face of another of said surrounding of said holding hole and said part of said second plastic part, and said terminal side projected portion with a bonding face of another of said surrounding of said connection terminal and said surrounding of said terminal introducing hole, respectively;

applying an ultrasonic wave to bonding portions of said first and second plastic parts so as to melt said hole side projected portion and said terminal side projected portion; and

bonding said surrounding portion of said holding hole to said part of said second plastic part, and said surrounding portion of said connection terminal to said surrounding of said terminal introducing hole, respectively.

10. (Withdrawn) The method of bonding the plastic parts according to claim 7, further comprising:

providing a third plastic part so that a hole side projected portion are provided at either one of a surrounding of a holding hole for holding a wiring board provided in said third

plastic part and a part of said first plastic part which is opposed to said surrounding of said holding hole;

stacking said third plastic part to said first plastic part;

applying an ultra sonic wave to bonding portions of said first plastic part and the third plastic part so as to melt the hole side projected portion; and

bonding said surrounding portion of said holding hole provided in said third plastic part to said first plastic part.

11. (Withdrawn) The method of bonding the plastic parts according to claim 8, further comprising:

providing a third plastic part so that a hole side projected portion are provided at either one of a surrounding of a holding hole for holding a wiring board provided in said third plastic part and a part of said first plastic part which is opposed to said surrounding of said holding hole;

stacking said third plastic part to said first plastic part;

applying an ultra sonic wave to bonding portions of said first plastic part and the third plastic part so as to melt the hole side projected portion; and

bonding said surrounding portion of said holding hole provided in said third plastic part to said first plastic part.

12. (Withdrawn) The method of bonding the plastic parts according to claim 9, further comprising:

providing a third plastic part so that a hole side projected portion are provided at either one of a surrounding of a holding hole for holding a wiring board provided in said third plastic part and a part of said first plastic part which is opposed to said surrounding of said holding hole;

stacking said third plastic part to said first plastic part;

applying an ultra sonic wave to bonding portions of said first plastic part and the third plastic part so as to melt the hole side projected portion; and

bonding said surrounding portion of said holding hole provided in said third plastic part to said first plastic part.

13. (Withdrawn) The method of bonding the plastic parts according to claim 8, wherein a terminal side projected portion is provided at the surrounding of said connection terminal in said first plastic part and constituted by a shape of a wedge capable of being brought into contact with a peripheral edge of said connection terminal introducing hole in said second plastic part.

14. (Withdrawn) The method of bonding the plastic parts according to claim 9, wherein a terminal side projected portion is provided at the surrounding of said connection terminal in said first plastic part and constituted by a shape of a wedge capable of being brought into contact with a peripheral edge of said connection terminal introducing hole in said second plastic part.

15. (Withdrawn) The method of bonding the plastic parts according to claim 11, wherein a terminal side projected portion is provided at the surrounding of said connection terminal in said first plastic part and constituted by a shape of a wedge capable of being brought into contact with a peripheral edge of said connection terminal introducing hole in said second plastic part.

16. (Withdrawn) The bonding structure according to claim 1, wherein an electric wire connected to the wiring board is further insert-molded to the first plastic part.

17. (Withdrawn) The method of bonding the plastic parts according to claim 7, wherein an electric wire connected to the wiring board is further insert-molded to the first plastic part.

18. (Withdrawn) The method of bonding the plastic parts according to claim 8, wherein an electric wire connected to the wiring board is further insert-molded to the first plastic part.

19. (Withdrawn) The method of bonding the plastic parts according to claim 9, wherein an electric wire connected to the wiring board is further insert-molded to the first plastic part.

20. (New) The bonding structure according to claim 1, wherein said surrounding of said holding hole is ring-shaped.

21. (New) The bonding structure according to claim 3, wherein said surrounding of said holding hole is ring-shaped.
22. (New) The bonding structure according to claim 2, wherein said surrounding of said connection terminal is wedge-shaped.
23. (New) The bonding structure according to claim 3, wherein said surrounding of said connection terminal is wedge-shaped.
24. (New) The bonding structure according to claim 1, wherein said plastic material selectively located in an area surrounding said holding hole is raised from a bonding face of the first plastic part.
25. (New) A door latch component for a vehicle, comprising:
 - a door latch component comprising a plastic bonding member;
 - wherein the plastic bonding member comprises a bonding structure as defined in claim 1.